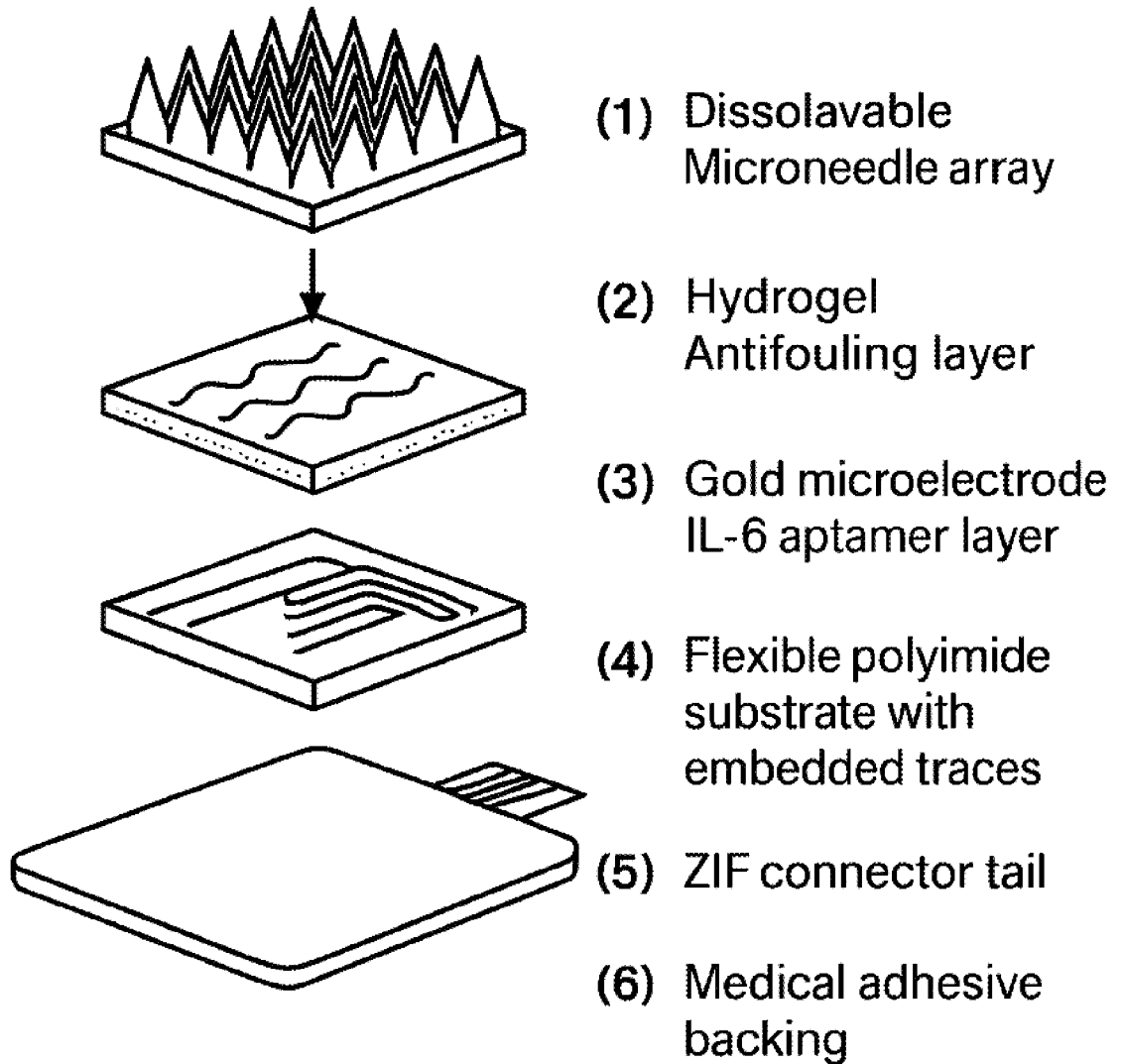
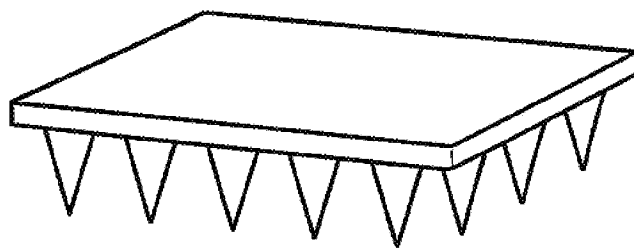


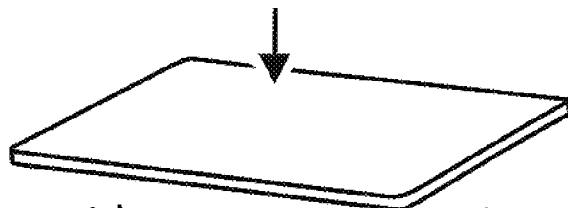
# Figures

Fig 1:

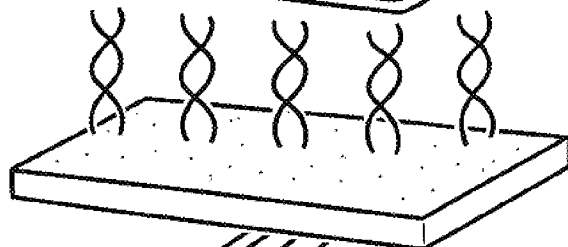




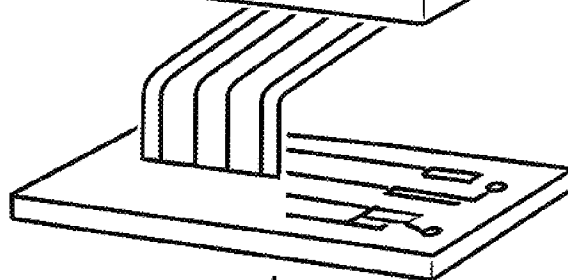
(1) Dissolvable  
Microneedle Array



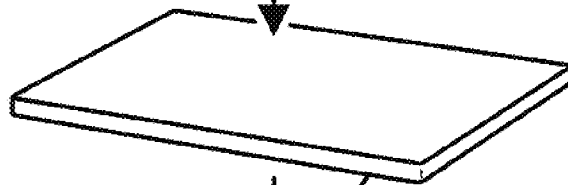
(2) Hydrogel  
Antifouling Layer



(3) Gold  
Microelectrode  
IL-6 Aptamer Layer



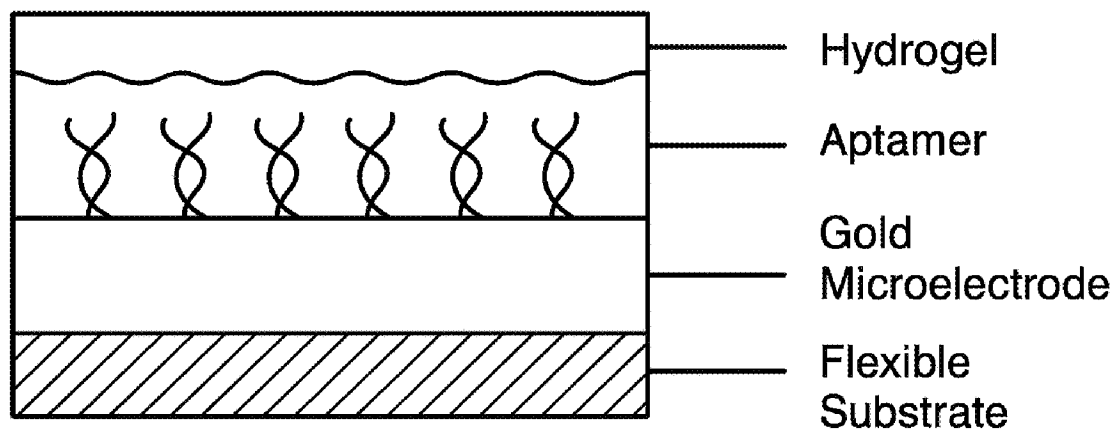
(4) Flexible  
Polyimide  
Substrate with  
Embedded Traces



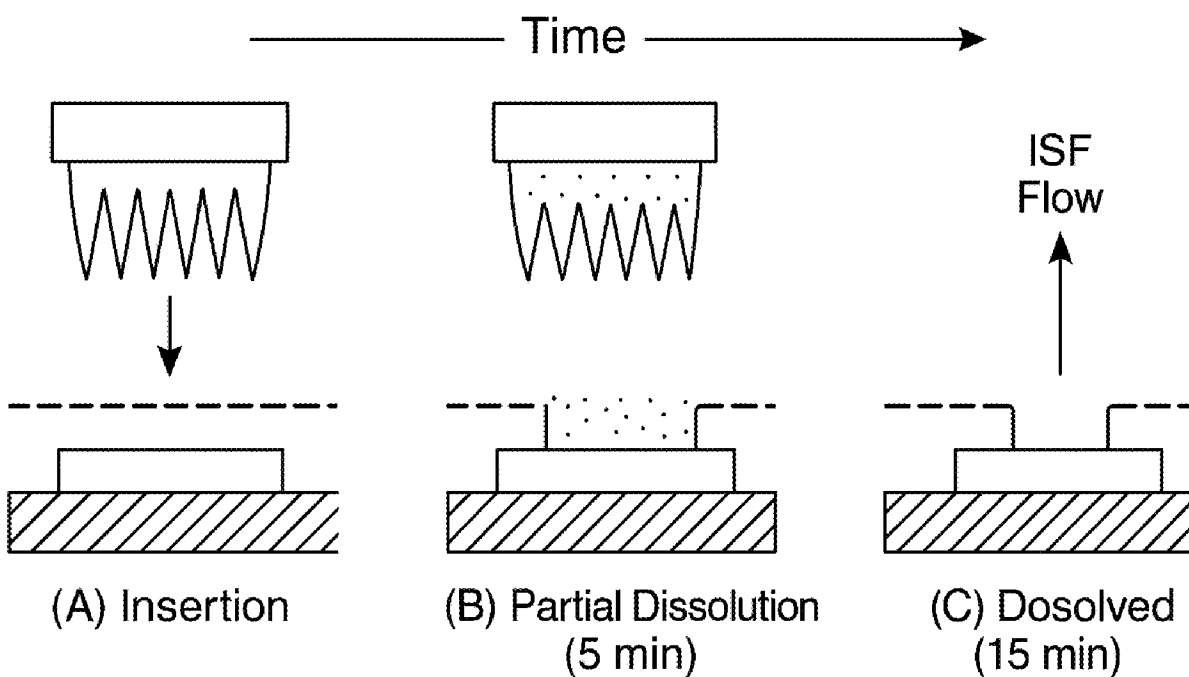
(5) ZIF  
Connector Tail



(6) Medical  
Adhesive Backing

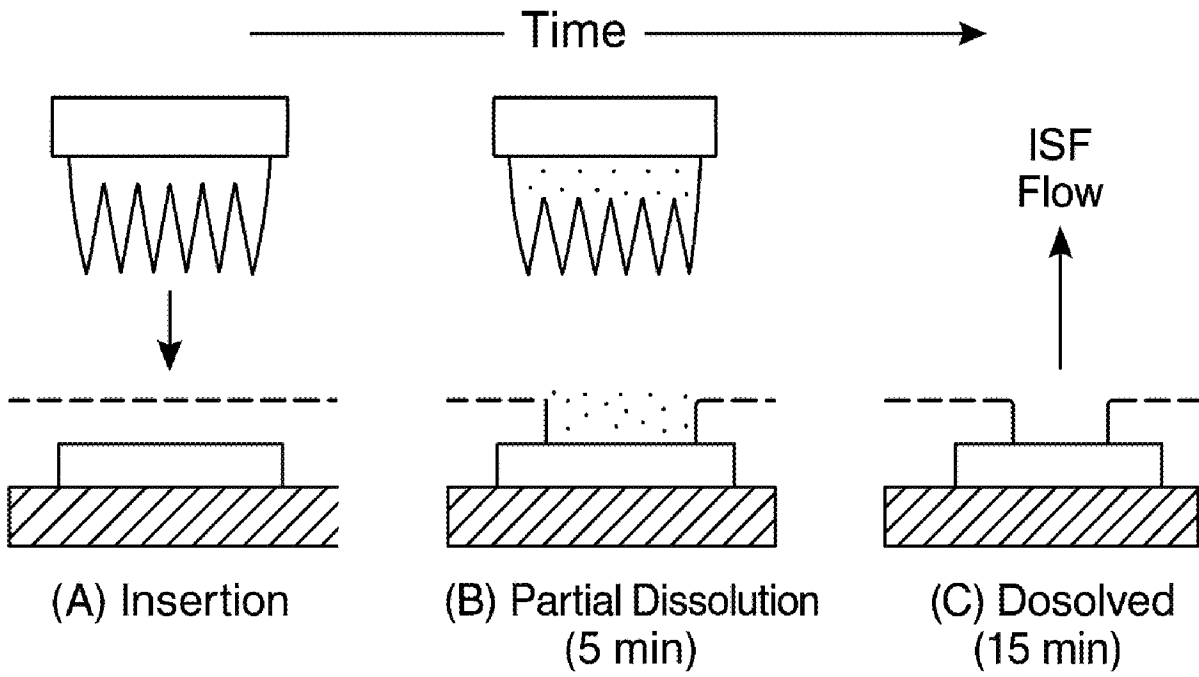


**FIG. 5-2**

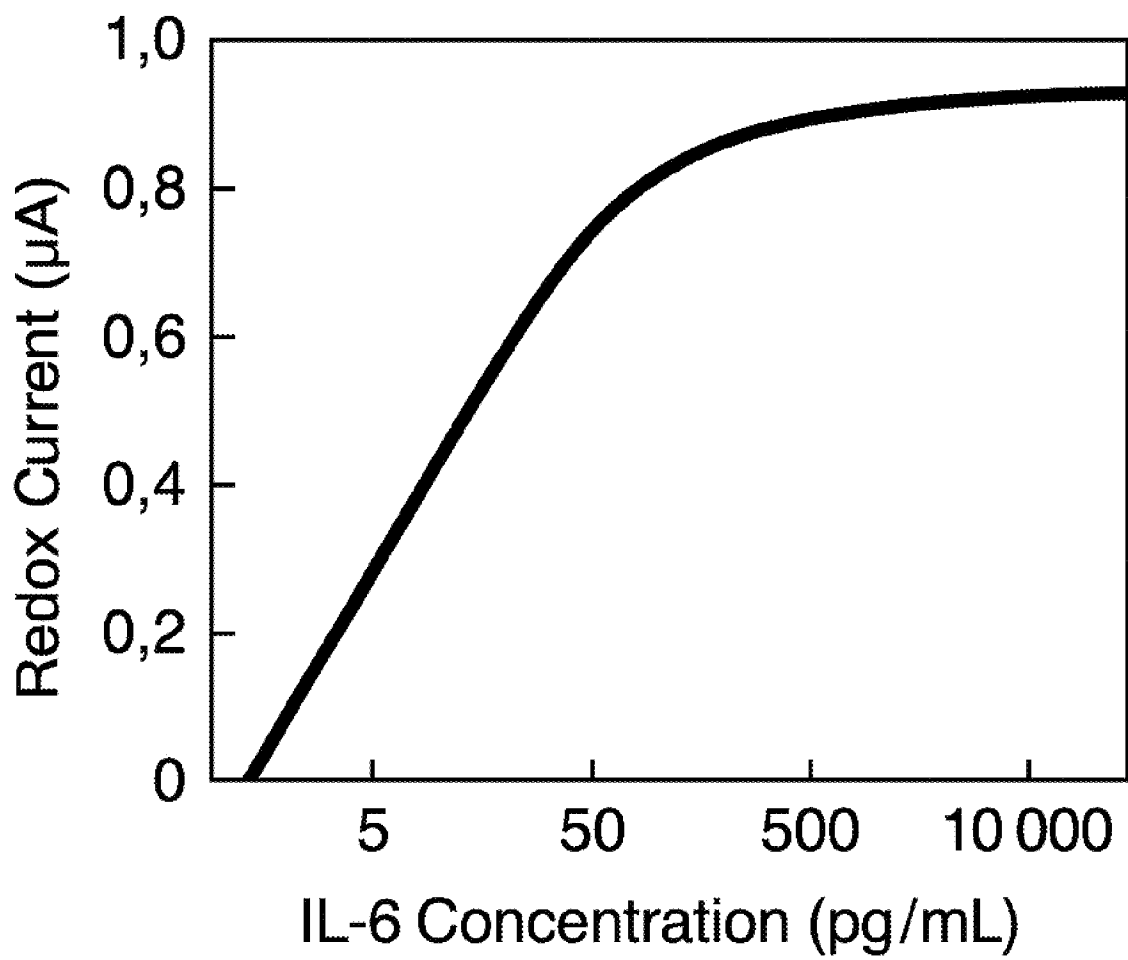


Layered insertion-dissolution time-course

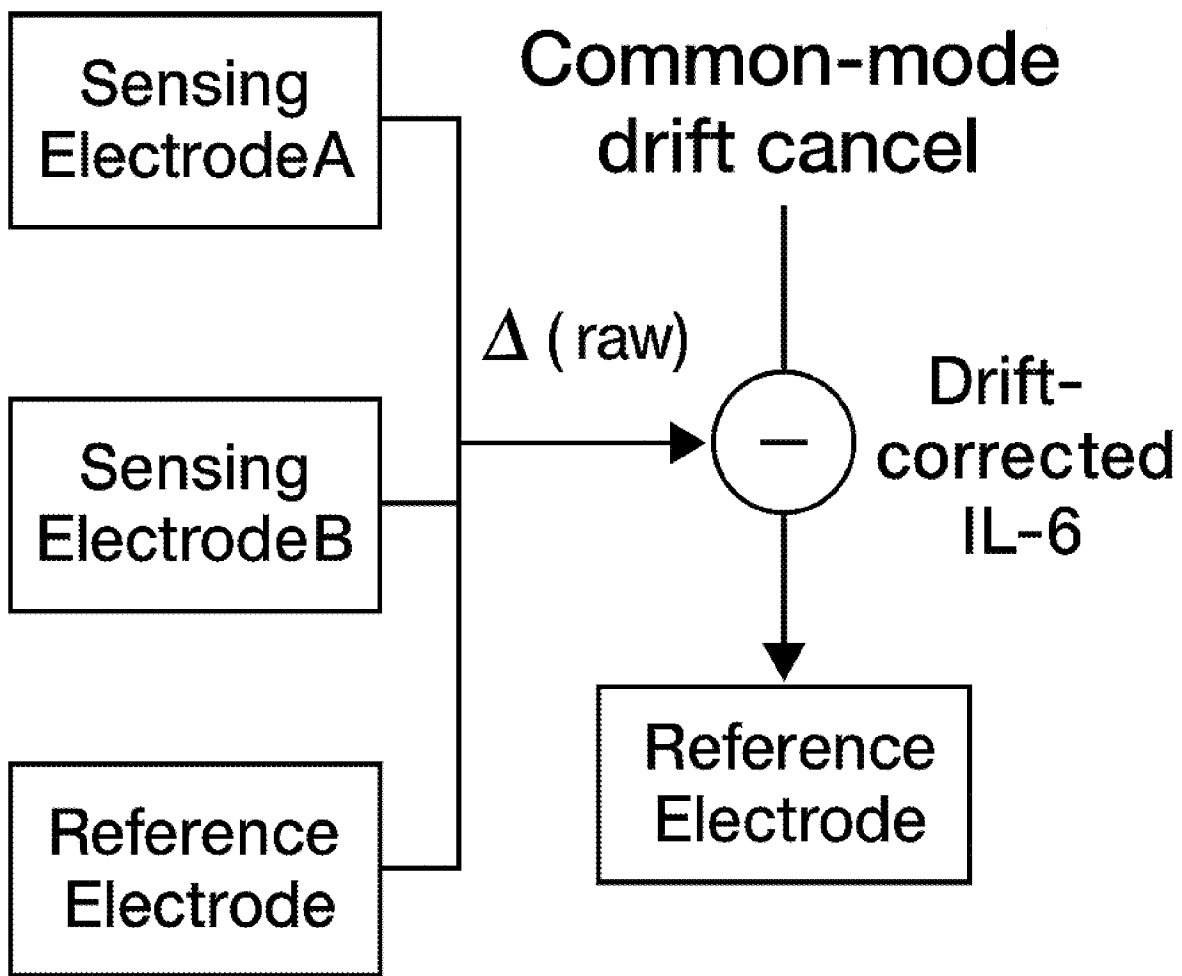
Fig 3



Layered insertion-dissolution time-course

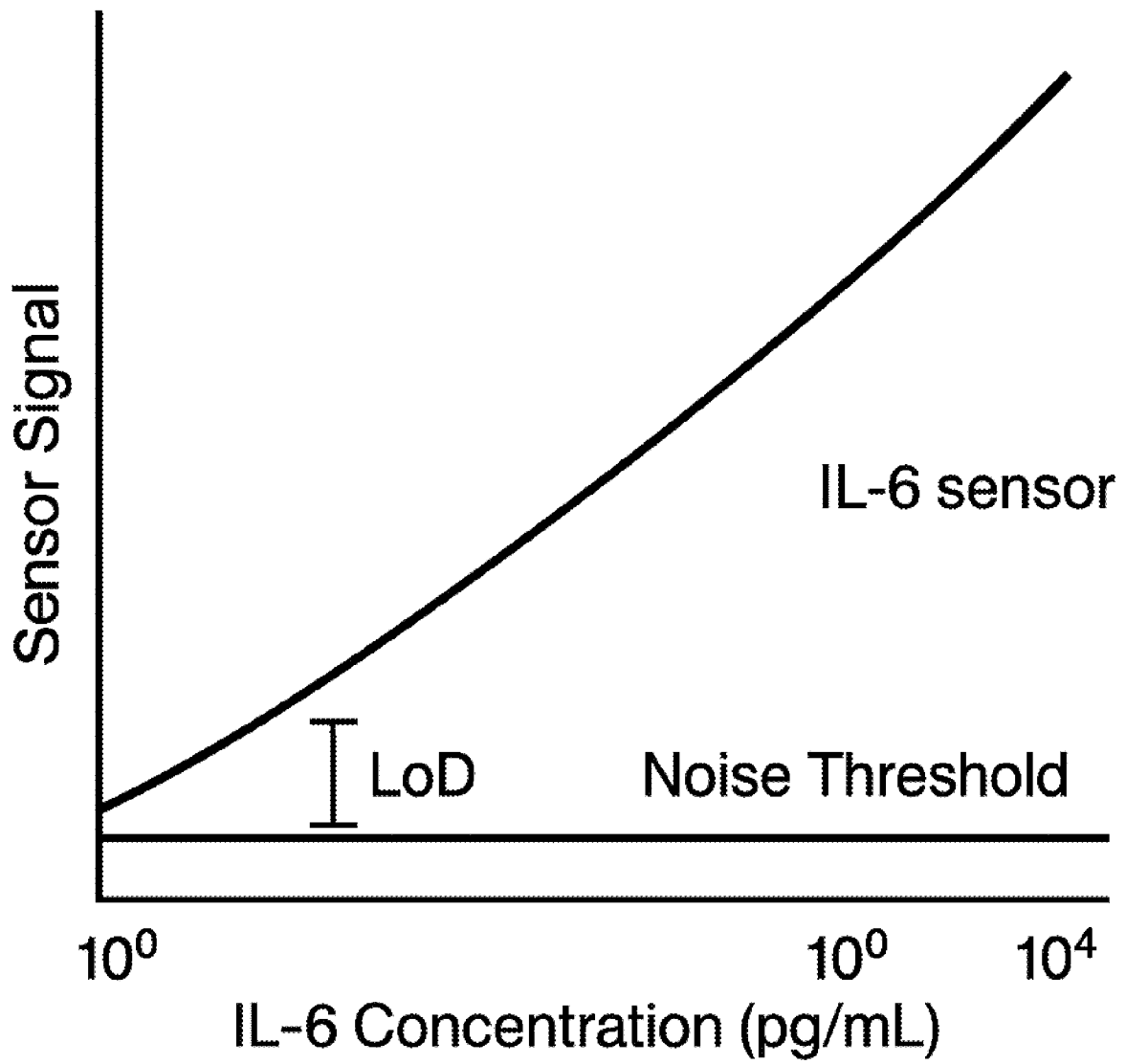


**Fig. 5-4**

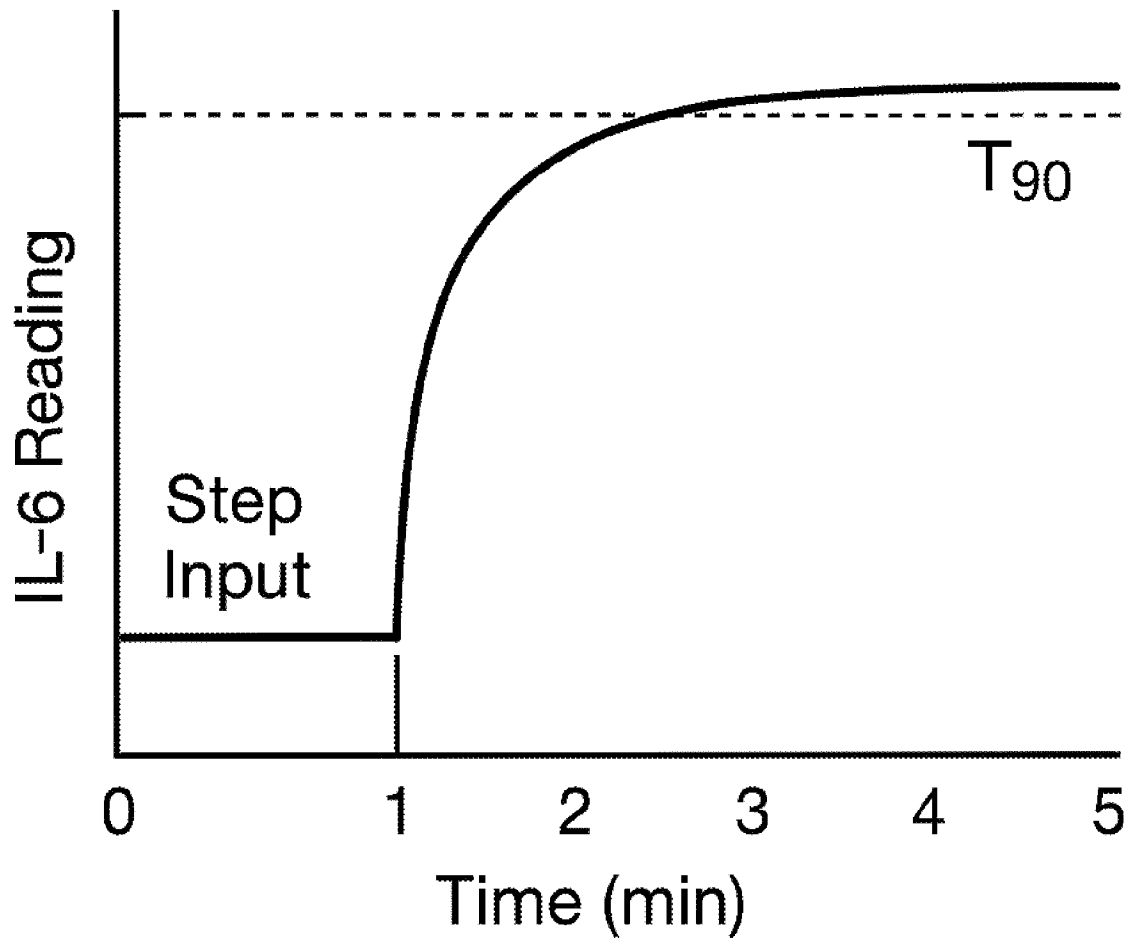


**FIG. 5-5**

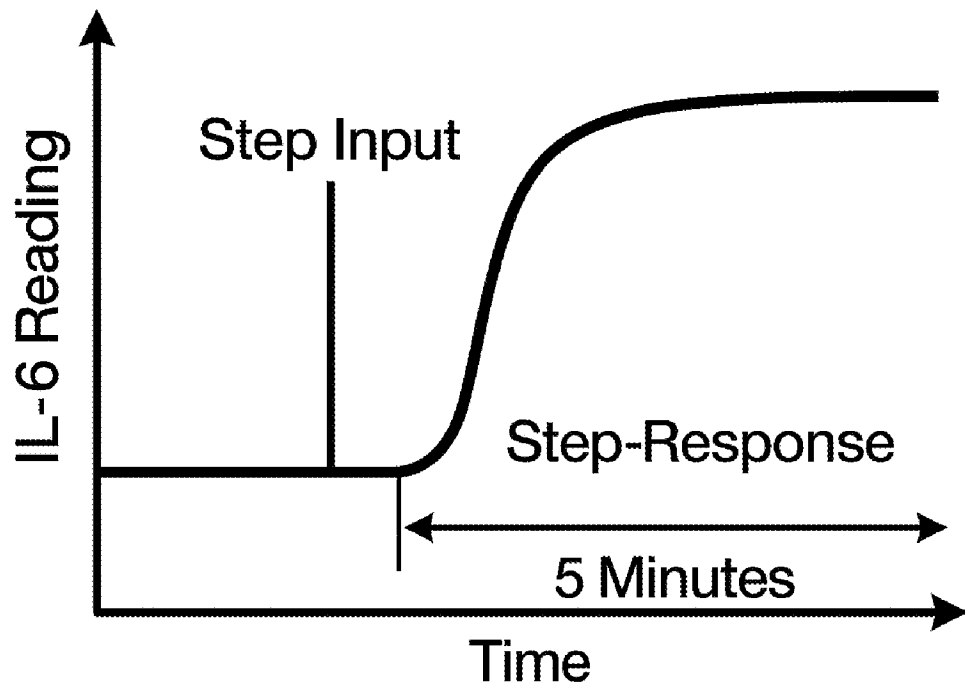
Dual-channel redundancy & drift-



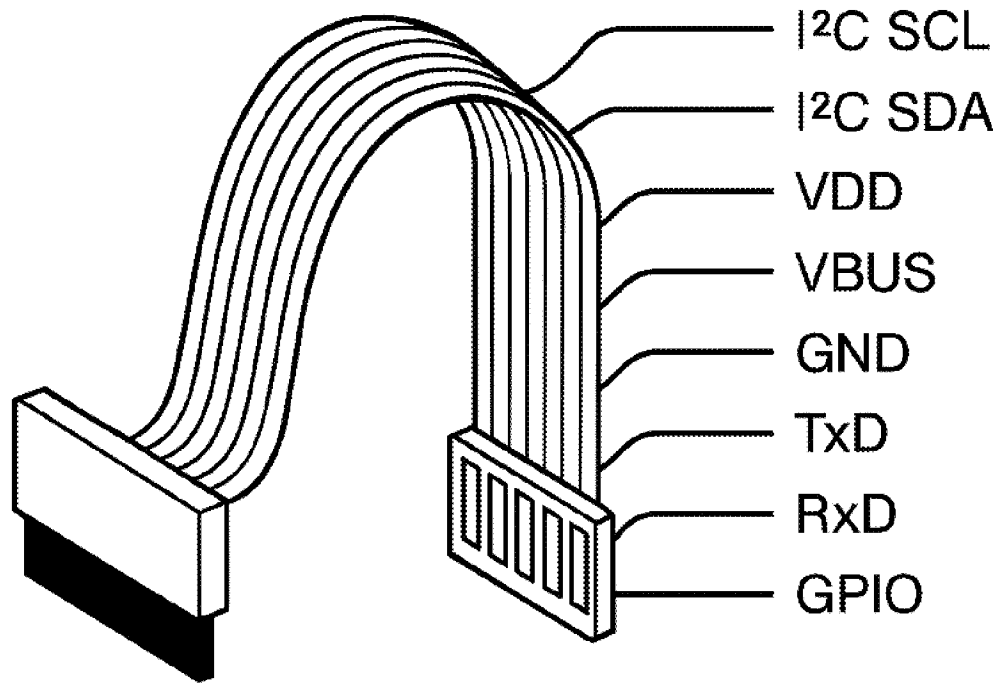
**FIG. 5-6**



**Fig. 5-7**



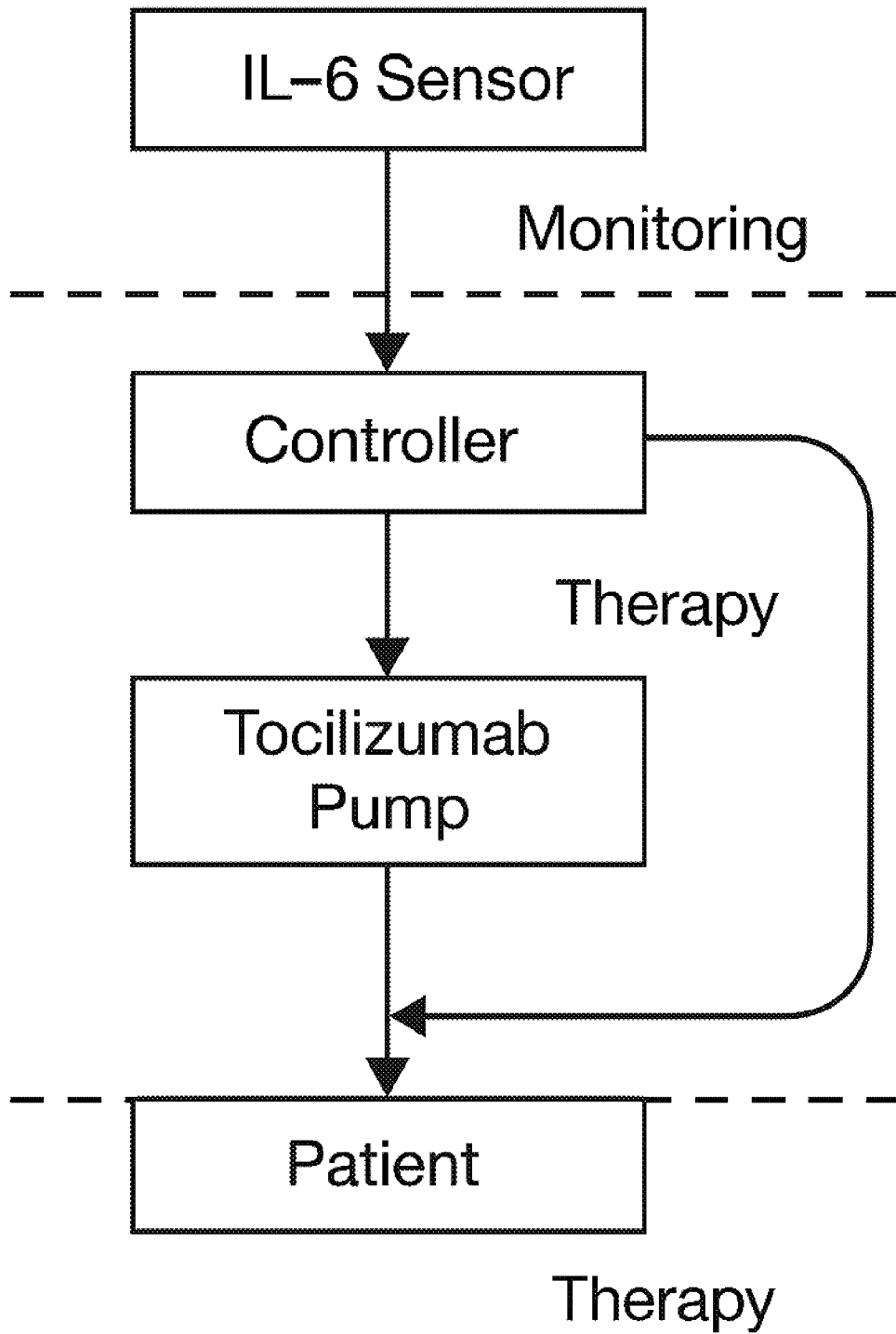
**Fig. 5-7**



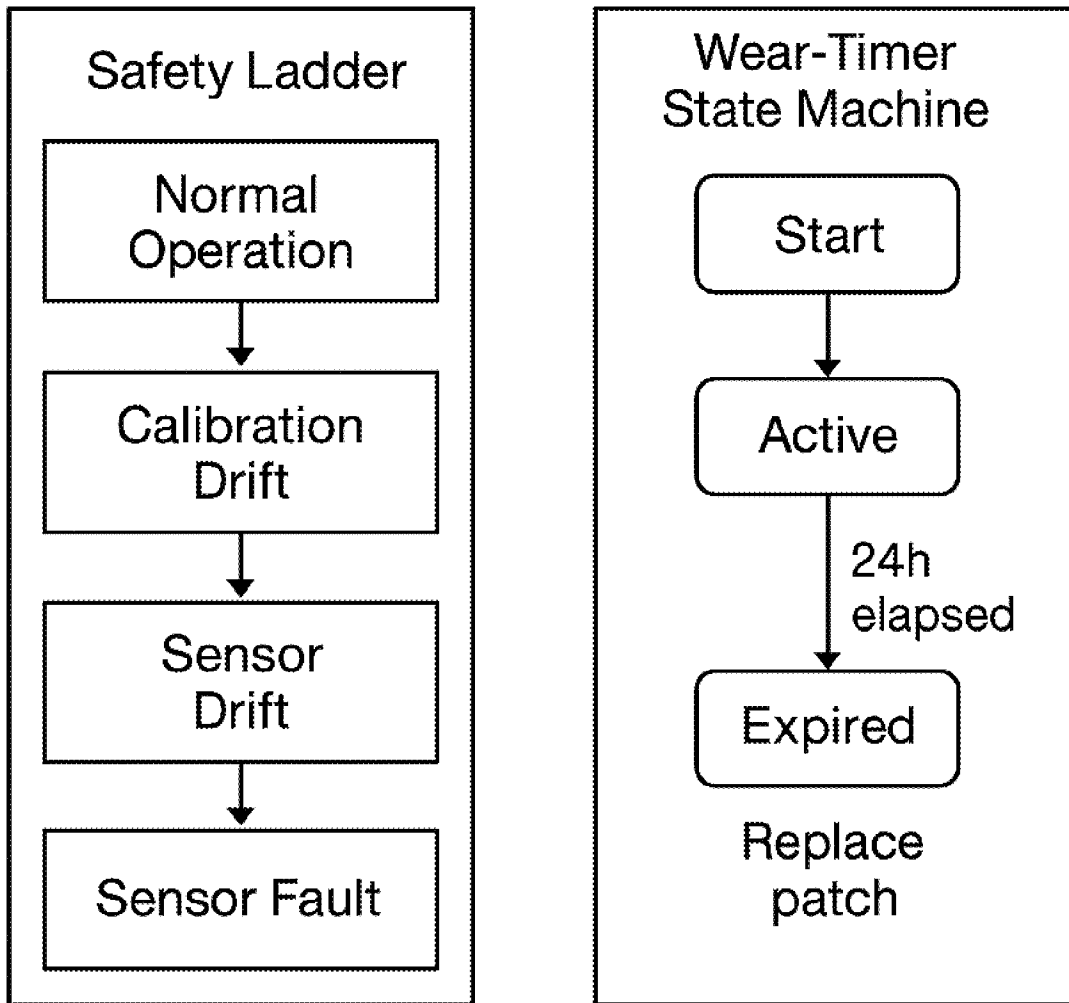
## FIG. 5-8

Hot-swap ZIF tail and sensor-bus pin-out schematic

Fig 5-9:



**Fig. 5**  
Closed-loop immunomodulator



**FIG. 5-10**

Calibration	0x00
UID	0x1F
Wear-Timer	0x20
Manufacturing	0x40
Status	0x6F
Spare	0x70
Checksum	0x7F

**FIG. 5-11**

EEPROM address map  
of IL-6 module